INTEGRATED CIRCUITS



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FEATURES

- · Requires very few external components
- Flexible in use quad, single ended or stereo BTL
- I²C-bus control
- Dynamic distortion detector
- Thermal protection
- Output status information
- Power supply dip detection
- High output power
- MUTE/sleep mode by writing to I²C-bus
- Stand-by mode
- Fixed gain
- Good ripple rejection
- Load dump protection
- AC/DC short circuit safe to ground and $\ensuremath{\mathsf{V}_\mathsf{P}}$
- Reverse polarity safe
- Low offset voltage at output
- Capable of handling high energy at outputs ($V_P = 0 V$)

QUICK REFERENCE DATA



- Electrostatic discharge protection
- No switch-ON/switch-OFF plop
- Flexible leads
- Low thermal resistance
- Identical inputs (inverting and non-inverting).

DESCRIPTION

The TDA1551Q is an integrated class-B output amplifier encased in a 17-lead single-in-line plastic power package. The device contains 4×11 W single-ended (SE) or 2×22 W BTL amplifiers and is intended for use in car radio applications.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _P	supply voltage range	operating	6	14.4	18	V
V _P	supply voltage	non-operating	_	_	30	V
IP	total quiescent current		_	80	160	mA
Quad-sing	le-ended application				1	T.
Po	output power	$R_L = 4 \Omega$; THD = 10 %	-	6	-	W
		R_L = 2 Ω ; THD = 10 %	_	11	_	W
V _{no}	output voltage noise	R _S = 0 Ω	-	50	-	μV
Stereo BT	L application			•		
Po	output power	$R_L = 4 \Omega$; THD = 10 %	-	22	-	W
V _{no}	output voltage noise	R _S = 0 Ω	_	70	_	μV
ΔV_{o}	DC output offset voltage		_	_	100	mV

ORDERING INFORMATION

EXTENDED TYPE	PACKAGE					
NUMBER	PINS	PIN POSITION	MATERIAL	CODE		
TDA1551Q	17	SIL bent to DIL	plastic	SOT243R ⁽¹⁾		

Note

1. SOT243-1; 1996 September 06.

inverting input 1 TDA1551Q 60 kΩ output 1 1.8 kΩ TEMP SENSE DDD 60 kΩ input 1 output 2 1.8 kΩ erial clock line * voltage I2C-BUS 14.9 KΩ ☜ supply voltage ripple rejection 16.2 kΩ ф referenc T nverting input 2 60 KΩ 12 output 18.1 positive supply voltage positive supply voltage 2 1 60 κΩ inverting input 2 10 output 3 1.8 κΩ Œ 18.1 kΩ age refe Γ Τ power ground 2 signal ground power ground 1 7228122 Fig.1 Block diagram.

PINNING

SYMBOL	PIN	DESCRIPTION
–INV1	1	non-inverting input 1
INV1	2	inverting input 1
GND	3	signal ground
V _{PRR}	4	supply voltage ripple rejection
V _{p1}	5	positive supply voltage 1
OUT1	6	output 1
GND1	7	power ground 1
OUT2	8	output 2
SB	9	standby
OUT3	10	output 3
GND2	11	power ground 2
OUT4	12	output 4
V _{p2}	13	positive supply voltage 2
INV2	14	inverting input 2
–INV2	15	non-inverting input 2
SCL	16	serial clock line
SDA	17	serial data line



FUNCTIONAL DESCRIPTION

The TDA1551Q contains four identical amplifiers with differential input stages (two inverting and two non-inverting) which can be used in SE or BTL applications. The gain of each amplifier is fixed at 20 dB for SE and 26 dB for BTL. The device also contains an I²C-bus facility which operates in the read or write mode.

In the **write** mode the device can be switched to either the sleep condition (low sleep current of 0.6 mA typ.), the MUTE condition or the ON condition.

In the **read** mode an 8-bit status word is available. Data bits D0 to D3 contain status information of each of the 4 outputs. If the device is switched to the ON or MUTE condition and there is a short-circuit at one or more outputs, the power transistors will be outside their safe operating area consequently one or more bits of D0 to D3 will be HIGH. Bits D0 to D3 are LOW when in the normal safe operating area. Bit D4 is normally LOW if one or more channels reaches the clipping level D4 will go HIGH. Bit D5 is normally LOW, if the crystal temperature reaches 150 °C D5 will go HIGH. After a power-on reset bit 7 will go HIGH and a dip in the power supply will be noticed. Bit 7 will go LOW after the l²C-bus is read. When pin 9 is LOW the device will switch OFF and the supply current will be reduced to 0.1 mA (max.).



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LIMITING VALUES

In accordance with the Absolute Maximum System (IEC134)

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
Supply volta	age			
VP	operating voltage	_	18	V
VP	non-operating voltage	-	30	V
	load dump protect	_	45	V
IOSM	non-repetitive peak output current	-	6	A
IORM	repetitive peak output current	-	4	A
T _{stg}	storage temperature range	-55	150	°C
Tc	crystal temperature	-	150	°C
V _{Psc}	AC/DC short-circuit safe voltage	-	18	V
	energy handling capability at outputs $(V_P = 0)$	-	200	mJ
V _{Pr}	reverse polarity	-	6	V
P _{tot}	total power dissipation	_	60	W

QUALITY SPECIFICATION

Electrostatic handling.

SYMBOL	PINS	MIN.	MAX.	UNIT					
Human body model; R _S = 1500 Ω ; C = 100 pF									
V _{es}	1, 2, 14, 15, 16, and 17	-1.5	+1.5	kV					
	other	-2	+2	kV					
Machine mo	del; $R_S = 0 \Omega$; C = 200 pF								
V _{es}	1, 2, 14, 15, 16, and 17	-100	+100	V					
	other	-200	+200	V					

THERMAL RESISTANCE

SYMBOL	PARAMETER	THERMAL RESISTANCE
R _{th j-c}	from junction to case (Fig.3)	1.5 K/W
R _{th j-a}	from junction to ambient in free air	40 K/W

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DC CHARACTERISTICS

 V_P = 14.4 V; T_{amb} = 25°C' measurements in accordance with Fig.6 unless otherwise stated.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply			·	•		•
V _P	supply voltage	note 1	6	14.4	18	V
I _P	quiescent current		-	80	160	mA
Vo	DC output voltage	note 2	-	6.9	-	V
ΔV _o	DC output offset voltage		-	-	100	mV
MUTE/slee	p/standby		·	•		•
Vo	output signal in MUTE position	V _{I(max)} = 1 V; f = 20 Hz to 10 kHz	-	_	2	mV
I _P	DC current in sleep condition	V9 > 3V	_	0.6	1	mA
I _P	DC current in standby condition	V9 < 2 V	_	-	0.1	mA
$ \Delta V_o $	DC output offset voltage		-	-	100	mV

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AC CHARACTERISTICS

 V_{P} = 14.4 V; T_{amb} = 25°C; f = 1 kHz; R_{L} = 4 $\Omega;$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Stereo BT	L application (Fig.7)		•	•		-
Po	output power	THD = 0.5%	15	17	-	W
			20	22	-	W
Po	output power	V _P = 13.2V				
		THD = 0.5%	-	12	-	W
		THD = 10%	-	17	-	W
THD	total harmonic distortion	P _O = 1 W	-	0.05	-	%
В	power bandwidth	THD = 0.5%; $P_O = -1 dB$ with respect to 15 W	-	20 - 15000	-	Hz
f _{LOW}	low frequency roll-off	at –3 dB; note 3	-	25	-	Hz
f _{HIGH}	high frequency roll-off	at –1 dB	20	-	-	kHz
Gv	closed loop voltage gain		25	26	27	dB
V _{PRR}	supply voltage ripple rejection	ON; note 4	48	-	-	dB
		MUTE; note 4	48	-	-	dB
		standby; note 4	80	-	-	dB
z _i	input impedance		25	30	38	kΩ
V _{no}	noise output voltage	ON; R _S = 0; note 5	-	70	-	μV
		ON; $R_S = 10 \text{ k}\Omega$; note 5	-	100	200	μV
		MUTE; notes 5 and 6	-	60	-	μV
α	channel separation	R _S = 10 kΩ	40	-	-	dB
$ \Delta G_v $	channel unbalance		_	_	1	dB
	dynamic distortion detector switch level		-	3.5	_	%
Quad sing	le-ended application (Fig.6)	·				•
Po	output power	THD = 0.5%; note 7	4	5	_	W
		THD = 10%; note 7	5.5	6	_	w
Po	output power	$R_L = 2 \Omega$				
		THD = 0.5%; note 7	7.5	8.5	_	W
		THD = 10%; note 7	10	11	_	W
THD	total harmonic distortion	P _O = 1 W	_	0.05	_	%
fLOW	low frequency roll-off	at –3 dB; note 3	_	25	_	Hz
f _{HIGH}	high frequency roll-off	at –1 dB	20	_	_	kHz
G _v	closed loop voltage gain		19	20	21	dB
V _{PRR}	supply voltage ripple rejection	ON; note 4	48	_	_	dB
		MUTE; note 4	48	_	_	dB
		stand-by; note 4	80	_	_	dB
Z _i	input impedance		50	60	75	kΩ
V _{no}	noise output voltage	ON; R _S = 0; note 5	_	50	_	μV
		ON; $R_S = 10 \text{ k}\Omega$; note 5	_	70	100	μV

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT	
		MUTE; notes 5 and 6	_	60	_	μV	
α	channel separation	R _S = 10 kΩ	40	_	_	dB	
$ \Delta G_v $	channel unbalance		_	_	1	dB	
	dynamic distortion detector switch level		-	3.5	-	%	
l ² C-bus (se	e I2C-bus protocol)		•			•	
VIH	input voltage HIGH		3	_	5.5	V	
V _{IL}	input voltage LOW		- 0.3	_	1.5	V	
I _{IH}	input current HIGH	V = 5.5 V	-10	_	10	μA	
IIL	input current LOW	V = GND	-10	_	10	μA	
V _{OL}	output voltage LOW	I _L = 3 mA	_	_	0.4	V	
Power-on	reset (increasing supply voltage	e)	·			·	
VP	start of reset		0.5	-	-	V	
	end of reset		_	_	5	V	
Standby (p	bin 9)			•		•	
V ₉	input voltage HIGH		3	-	VP	V	
	input voltage LOW		_	_	2	V	

Notes to the characteristics

- 1. The circuit is DC adjusted at $V_P = 6$ V and AC operating at $V_P = 8$ to 18 V.
- 2. At 18 V < V_P < 30 V the DC output voltage < $V_P/2$.
- 3. Frequency response externally fixed.
- 4. Ripple rejection measured at the output with a source impedance of 0 Ω and at frequency of 100 Hz to 10 kHz (amplitude = 2 V(p-p)).
- 5. Noise voltage measured in a bandwidth of 20 Hz to 20 kHz.
- 6. Noise output voltage independent of $R_S (V_I = 0 V)$.
- 7. Output power is measured directly at the output pins of the IC.

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I²C-bus protocol



Table 1 WRITE definition $(R/\overline{W} = LOW)$

MSB		DATA						Function
D7	D6	D5	D4	D3	D2	D1	D0	
0	0	0	0	0	0	0	0	SLEEP condition
0	0	0	0	0	0	0	1	MUTE condition
0	0	0	0	0	0	1	0	not allowed ⁽¹⁾
0	0	0	0	0	0	1	1	ON condition ⁽²⁾

Notes

- 1. For test purposes only; I²C-bus is in the ON condition, amplifier is in the stand-by condition.
- 2. To get into the ON condition without switch-on plops, the device should be switched from the SLEEP condition to the MUTE condition and then, after a period of 150 ms, to the ON condition.

Bit D0 switches from SLEEP to the ON condition

Bit D1 switches the MUTE condition

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Table 2	READ definition	(R/W = HIGH)
		(1000 - 1001)

D7 ⁽¹⁾⁽²⁾	D6	D5 ⁽³⁾⁽⁴⁾	D4 ⁽⁵⁾⁽⁶⁾	D3 ⁽⁷⁾	D2 ⁽⁷⁾	D2 ⁽⁷⁾	D0 ⁽⁷⁾

Notes

- 1. LOW after reading I²C-bus.
- 2. HIGH after power-on reset.
- 3. LOW if crystal temperature < 150° C.
- 4. HIGH if crystal temperature reaches 150°C.
- 5. LOW if not clipping.
- 6. HIGH if one or more channels are clipping.
- 7. output status information.

If the device is sinewave driven bit D4 will be HIGH if the THD in one or more channels exceeds 3.5%.

Table 3Fault conditions

DATA		MSB		
D3	D2	D1	D0	FUNCTION
0	0	0	0	all output power transistors in the normal
				safe operating condition
_	-	-	1	fault condition pin 6
_	-	1	-	fault condition pin 8
_	1	_	_	fault condition pin 10
1	_	_	-	fault condition pin 12

If more outputs are in a fault condition (e.g. short-circuit) then more bits, D3 to D0, will be HIGH.









PACKAGE OUTLINE



SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Soldering by dipping or by wave

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\,max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

Repairing soldered joints

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

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DEFINITIONS

Data sheet status					
Objective specification	This data sheet contains target or goal specifications for product development.				
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	This data sheet contains final product specifications.				
Limiting values					
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.					
Application information					

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

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